## Express Mail No. EV 346 810 935 US.

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Claire RICHTARCH

Confirmation No.6886

Application No: 10/671,812

Group Art Unit: 1762

Filing Date: September 25, 2003

Examiner:

For:

METHOD OF PREPARING A SURFACE

OF A SEMICONDUCTOR WAFER TO

MAKE IT EPIREADY

Atty. Docket No.: 4717-11300

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450 Sir:

Pursuant to applicants' duty of disclosure under 37 C.F.R. 1.56, enclosed is a PTO form 1449 which lists four (4) cited references for the Examiner's review and consideration. A copy of the Preliminary Search Report is enclosed.

It is respectfully requested that these references be made of record in this application by the Examiner's completion and return of the PTO Form 1449.

No fee or certification is believed to be due for this submission since the filing of this statement is being submitted prior to the issuance of the first office action for this application. Should any fees be required, however, please charge such fees to **Winston & Strawn LLP** Deposit Account No. 50-1814.

Respectfully submitted,

Date:

May 7, 2004

Allan A. Fanucci

(Reg. No. 30,256)

WINSTON & STRAWN LLP CUSTOMER NO. 28765

**Enclosures** 

(212) 294-3311

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LIST OF REFERENCES CITED BY APPLICANT Form PTO-1449					4717-11300				
					APPLICANT:				
(Use several sheets if necessary)					Claire RICHTARCH				
					FILING DATE: GROUP:				
7 2004 [					September 25, 2003				
Claire RICHTARCH FILING DATE: September 25, 2003  U.S. PATENT DOCUMENTS									
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OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)									
	AC	Bruel, M. et al., "Smart-Cut": A Promising New SOI Material Technology, IEEE SOI Conference, October 1995, pp 178-179.							
	AD	Maleville et al., "Wafer Bonding and H-Implantation Mechanisms Involved In The Smart-Cut Technology", Materials Science and Engineering, 1997, pp. 14-19.							
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EXAMINER									
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not									
in conformance and not considered. Include copy of this form with next communication to applicant.									